Advanced materials and new device technologies are seeing greater and greater penetration by particle technology from nanometer to micron length scales. While it is readily apparent that nanoparticle-based CMP formulations are invaluable in furthering extant FAB performance by making multilayer device design practical, particles are becoming more and more important in conceptualizing and designing devices for the future. These inroads by particle technology will be described for electronic (and magnetic), photonic, and hybrid systems. Self-assembly principles will be used to illustrate more fanciful approaches to device fabrication with nanoparticles in future bottom-up design and synthesis.

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When: 1:30 p.m., Wednesday, Oct. 26, 2005
Where: Engineering Building, Room 2409

ALL ECE GTAs and GRAs MUST ATTEND at THE SEMINAR